



Material Content Data Sheet



Sales Product Name	BAS 70-02V H6327			Issued		16. January 2020		
MA#	MA001179706							
Package	PG-SC79-2-1			Weight*		1.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		18	
	noble metal	gold	7440-57-5	0.003	0.18		1791	
	inorganic material	silicon	7440-21-3	0.026	1.53	1.71	15296	17105
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		461	
	non noble metal	chromium	7440-47-3	0.002	0.14		1382	
	non noble metal	copper	7440-50-8	0.767	45.88	46.08	458893	460828
wire	non noble metal	copper	7440-50-8	0.002	0.13	0.13	1319	1319
encapsulation	organic material	carbon black	1333-86-4	0.007	0.44		4353	
	plastics	epoxy resin	-	0.124	7.40		74002	
	inorganic material	silicondioxide	60676-86-0	0.597	35.70	43.54	356952	435307
leadfinish	non noble metal	tin	7440-31-5	0.055	3.26	3.26	32642	32642
plating	noble metal	silver	7440-22-4	0.088	5.28	5.28	52799	52799
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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